

SiGe:C Low Noise Amplifier MMIC for GPS, GLONASS, Galileo and Compass

Rev. 3 — 18 January 2017

Product data sheet

1. Product profile

1.1 General description

The BGU7004 is, also known as the GPS1103M, an AEC-Q100 qualified Low Noise Amplifier (LNA) for GNSS receiver applications in a plastic leadless 6-pin, extremely small SOT886 package. The BGU7004 requires only one external matching inductor and one external decoupling capacitor.

The BGU7004 adapts itself to the changing environment resulting from co-habitation of different radio systems in modern cellular handsets. It has been designed for low power consumption and optimal performance when jamming signals from co-existing cellular transmitters are present. At low jamming power levels it delivers 16.5 dB gain at a noise figure of 0.85 dB. During high jamming power levels, resulting for example from a cellular transmit burst, it temporarily increases its bias current to improve sensitivity.

1.2 Features and benefits

- AEC-Q100 qualified (see <u>Section 9.1</u>)
- Covers full GNSS L1 band, from 1559 MHz to 1610 MHz
- Noise figure (NF) = 0.85 dB and gain (G_p) = 16.5 dB
- High input 1 dB compression point P_i (1dB) of −11 dBm
- High out of band IP3_i of 9 dBm
- Supply voltage 1.5 V to 2.85 V
- Power-down mode current consumption < 1 μA</p>
- Optimized performance at low supply current of 4.5 mA
- Integrated matching for the output
- Requires only one input matching inductor and one supply decoupling capacitor
- Input and output DC decoupled
- ESD protection on all pins (HBM > 2 kV)
- Integrated temperature stabilized bias for easy design
- Small 6-pin leadless package 1 mm × 1.45 mm × 0.5 mm
- 110 GHz transit frequency SiGe:C technology

1.3 Applications

 LNA for GPS, GLONASS, Galileo and Compass (BeiDou) in automotive applications like Toll Collection and Emergency Call.



LNA for GPS, GLONASS, Galileo and Compass (BeiDou) in smart phones, feature phones, tablet PCs, Personal Navigation Devices, Digital Still Cameras, Digital Video Cameras, RF Front End modules, complete GPS chipset modules and theft protection (laptop, ATM).

1.4 Quick reference data

Table 1. Quick reference data

f = 1559 MHz to 1610 MHz; $V_{CC} = 1.8 \text{ V}$; $P_i < -40 \text{ dBm}$; $T_{amb} = 25 \text{ °C}$; input matched to 50 Ω using a 5.6 nH inductor; unless otherwise specified.

Symbo I	Parameter	Conditions		Min	Тур	Max	Unit
V _{CC}	supply voltage	RF input AC coupled		1.5	-	2.85	V
I _{CC}	supply current	$V_{\text{ENABLE}} \ge 0.8 \text{ V}$					
		P _i < -40 dBm		3.2	4.5	5.7	mA
		$P_i = -20 \text{ dBm}$		8.1	11.6	14.4	mA
G _p	power gain	P _i < –40 dBm, no jammer		14	16.5	19	dB
		P _i = -20 dBm, no jammer		15	17.5	20	dB
NF	noise figure	P _i < −40 dBm, no jammer	[1]	-	0.85	1.2	dB
		P _i < –40 dBm, no jammer	[2]	-	0.9	1.3	dB
		P _i = -20 dBm, no jammer		-	1.2	1.6	dB
P _{i(1dB)}	input power at 1 dB gain compression	f = 1559 MHz to 1610 MHz					
		V _{CC} = 1.5 V		-15	-12	-	dBm
		V _{CC} = 1.8 V		-14	-11	-	dBm
		V _{CC} = 2.85 V		-11	-8	-	dBm
IP3 _i	input third-order intercept point	f = 1.575 GHz					
		V _{CC} = 1.5 V	[3]	5	8	-	dBm
		V _{CC} = 1.8 V	[3]	5	9	-	dBm
		V _{CC} = 2.85 V	[3]	5	12	-	dBm

[1] PCB losses are substracted.

[2] Including PCB losses.

[3] $f_1 = 1713 \text{ MHz}; f_2 = 1851 \text{ MHz}; P_1 = P_2 = -30 \text{ dBm}.$

2. Pinning information

Table 2. Pi	nning		
Pin	Description	Simplified outline	Graphic symbol
1	GND	o 5 4	
2	GND		4 5
3	RF_IN		3 - 6
4	V _{CC}		
5	ENABLE		2 1 <i>sym129</i>
6	RF_OUT	1 2 3 Transparent top view	

BGU7004

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3. Ordering information

Table 3. Ordering information								
Type number	Package							
	Name	Description	Version					
BGU7004	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body $1 \times 1.45 \times 0.5$ mm	SOT886					

4. Marking

Table 4. Marking codes	
Type number	Marking code
BGU7004	UY

5. Limiting values

Table 5.Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{CC}	supply voltage	RF input AC coupled		-0.5	3.1	V
V _{ENABLE}	voltage on pin ENABLE	$V_{CC} \ge 2.5 \text{ V}$		-0.5	3.1	V
		V_{CC} < 2.5 V	[2]	-0.5	V _{CC} + 0.6	V
V _{RF_IN}	voltage on pin RF_IN	DC				
		$V_{CC} \ge 3.0 \text{ V}$	[3]	-0.5	3.6	V
		V _{CC} < 3.0 V	[2][3]	-0.5	V _{CC} + 0.6	V
V _{RF_OUT}	voltage on pin RF_OUT	DC				
		$V_{CC} \ge 1.8 \text{ V}$	[3]	-0.5	3.6	V
		V _{CC} < 1.8 V	[2][3]	-0.5	V _{CC} + 1.8	V
Pi	input power			-	0	dBm
P _{tot}	total power dissipation	$T_{sp} \le 130 \ ^{\circ}C$	[1]		55	mW
T _{stg}	storage temperature			-65	150	°C
Tj	junction temperature			-	150	°C

[1] T_{sp} is the temperature at the soldering point of the emitter lead.

[2] Due to internal ESD diode protection, the applied voltage should not exceed the specified maximum in order to avoid excess current.

[3] The RF input and RF output are AC coupled through internal DC blocking capacitors.

6. Thermal characteristics

Table 6.	Thermal characteristics			
Symbol	Parameter	Conditions	Тур	Unit
R _{th(j-sp)}	thermal resistance from junction to solder point		225	K/W

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7. Characteristics

Table 7. Characteristics

f = 1559 MHz to 1610 MHz; $V_{CC} = 1.8 \text{ V}$; $V_{ENABLE} \ge 0.8 \text{ V}$; $P_i < -40 \text{ dBm}$; $T_{amb} = 25 \degree C$; input matched to 50 Ω using a 5.6 nH inductor; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _{CC}	supply voltage	RF input AC coupled		1.5	-	2.85	V
I _{CC}	supply current	$V_{\text{ENABLE}} \ge 0.8 \text{ V}$					
		P _i < -40 dBm		3.2	4.5	5.7	mA
		$P_i = -20 \text{ dBm}$		8.1	11.6	14.4	mA
		$V_{\text{ENABLE}} \leq 0.3 \text{ V}$		-	-	1	μA
T _{amb}	ambient temperature			-40	+25	+125	°C
G _p	power gain	T _{amb} = 25 °C					
		P _i < −40 dBm, no jammer		14	16.5	19	dB
		$P_i = -20 \text{ dBm}$, no jammer		15	17.5	20	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 850 \text{ MHz}$		15	17.5	20	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 1850 \text{ MHz}$		15	17.5	20	dB
		$-40 \text{ °C} \leq T_{amb} \leq +125 \text{ °C}$					
		P _i < −40 dBm, no jammer		13	-	20	dB
		$P_i = -20 \text{ dBm}$, no jammer		14	-	21	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 850 \text{ MHz}$		14	-	21	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 1850 \text{ MHz}$		14	-	21	dB
RL _{in}	input return loss	P _i < -40 dBm		5	8	-	dB
		$P_i = -20 \text{ dBm}$		6	10	-	dB
RL _{out}	output return loss	P _i < -40 dBm		10	20	-	dB
		$P_i = -20 \text{ dBm}$		10	14	-	dB
ISL	isolation			20	23	-	dB
NF	noise figure	T _{amb} = 25 °C					
		P _i < −40 dBm, no jammer	<u>[1]</u>	-	0.85	1.2	dB
		P _i < −40 dBm, no jammer	[2]	-	0.9	1.3	dB
		$P_i = -20 \text{ dBm}$, no jammer		-	1.2	1.6	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 850 \text{ MHz}$		-	1.1	1.5	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 1850 \text{ MHz}$		-	1.3	1.7	dB
		$-40 \text{ °C} \le T_{amb} \le +125 \text{ °C}$					
		P _i < −40 dBm, no jammer		-	-	1.8	dB
		$P_i = -20 \text{ dBm}$, no jammer		-	-	2.0	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 850 \text{ MHz}$		-	-	1.9	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 1850 \text{ MHz}$		-	-	2.1	dB

Table 7. Characteristics ...continued

f = 1559 MHz to 1610 MHz; $V_{CC} = 1.8 \text{ V}$; $V_{ENABLE} \ge 0.8 \text{ V}$; $P_i < -40 \text{ dBm}$; $T_{amb} = 25 \degree \text{C}$; input matched to 50 Ω using a 5.6 nH inductor; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
P _{i(1dB)}	input power at 1 dB	f = 1559 MHz to 1610 MHz					
	gain compression	V _{CC} = 1.5 V		-15	-12	-	dBm
		V _{CC} = 1.8 V		-14	-11	-	dBm
		V _{CC} = 2.85 V		-11	-8	-	dBm
		f = 806 MHz to 928 MHz					
		V _{CC} = 1.5 V	[3]	-15	-12	-	dBm
		V _{CC} = 1.8 V	[3]	-14	-11	-	dBm
		V _{CC} = 2.85 V	[3]	-14	-11	-	dBm
		f = 1612 MHz to 1909 MHz					
		V _{CC} = 1.5 V	[3]	-13	-10	-	dBm
		V _{CC} = 1.8 V	[3]	-12	-9	-	dBm
		V _{CC} = 2.85 V	[3]	-10	-7	-	dBm
IP3 _i	input third-order intercept point	f = 1.575 GHz					
		V _{CC} = 1.5 V	[4]	5	8	-	dBm
		V _{CC} = 1.8 V	[4]	5	9	-	dBm
		V _{CC} = 2.85 V	[4]	5	12	-	dBm
t _{on}	turn-on time		[5]	-	-	2	μs
t _{off}	turn-off time		[5]	-	-	1	μs
K	Rollett stability factor			1	-	-	

[1] PCB losses are subtracted.

- [2] Including PCB losses.
- [3] Out of band.
- [4] $f_1 = 1713 \text{ MHz}$; $f_2 = 1851 \text{ MHz}$; $P_1 = P_2 = -30 \text{ dBm}$.
- [5] Within 10 % of the final gain.

Table 8.ENABLE (pin 5)

 $-40 \circ C \le T_{amb} \le +125 \circ C; \ 1.5 \ V \le V_{CC} \le 2.85 \ V$

V _{ENABLE} (V)	State
≤ 0.3	OFF
≥ 0.8	ON

8. Application information

8.1 GNSS LNA



Table 9.List of componentsFor schematics see Figure 1.

Component	Description	Value	Supplier	Remarks
C1	decoupling capacitor	1 nF	various	
IC1	BGU7004	-	NXP	
L1	high quality matching inductor	5.6 nH	Murata LQW15A	



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8.2 GPS front-end

The GPS LNA is typically used in a GPS front-end. A GPS front-end application circuit and its characteristics is provided here.



Table 10.List of componentsFor schematics see Figure 32.

Component	Description	Value	Supplier	Remarks
BPF1, BPF2	GPS SAW filter	-	Murata SAFEA1G57KE0F00	Alternatives from Epcos:
				• B9444
				Alternatives from Murata:
				 SAFEA1G57KH0F00
				 SAFEA1G57KB0F00
				Alternatives from Fujitsu:
				• FAR-F6KA-1G5754-L4AA
				• FAR-F6KA-1G5754-L4AJ
C1	decoupling capacitor	1 nF	Various	
IC1	BGU7004	-	NXP	
L1	high quality matching inductor	5.6 nH	Murata LQW15A	

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8.3 Characteristics GPS front-end

Table 11. Characteristics GPS front-end

 $f = 1575 \text{ MHz}; V_{CC} = 1.8 \text{ V}; V_{ENABLE} \ge 0.8 \text{ V}; \text{ power at LNA input } P_i < -40 \text{ dBm}; T_{amb} = 25 \text{ °C}; \text{ input and output matched to } 50 \Omega; unless otherwise specified.}$

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _{CC}	supply voltage	RF input AC coupled		1.5	-	2.85	V
I _{CC}	supply current			-	4.5	-	mA
G _p	power gain	power at LNA input P _i < -40 dBm	<u>[1]</u>	-	14.5	-	dB
		power at LNA input $P_i = -20 \text{ dBm}$	<u>[1]</u>	-	15.5	-	dB
RL _{in}	input return loss	power at LNA input P _i < -40 dBm	<u>[1]</u>	-	8.5	-	dB
		power at LNA input $P_i = -20 \text{ dBm}$	<u>[1]</u>	-	10.5	-	dB
RL _{out}	output return loss	power at LNA input P _i < -40 dBm	<u>[1]</u>	-	14.5	-	dB
		power at LNA input $P_i = -20 \text{ dBm}$	<u>[1]</u>	-	12.5	-	dB
NF	noise figure	power at LNA input P _i < -40 dBm	<u>[1]</u>	-	1.8	-	dB
		power at LNA input $P_i = -20 \text{ dBm}$	[1]	-	1.9	-	dB
P _{i(1dB)}	input power at 1 dB gain compression	f = 1575 MHz			-8.2		dBm
		f = 806 MHz to 928 MHz	[2]		31		dBm
		f = 1612 MHz to 1909 MHz	[2]		40		dBm
IP3 _i	input third-order intercept point		[3]		64		dBm
α	attenuation	f = 850 MHz	[4]	95	-	-	dBc
		f = 1850 MHz	[4]	90	-	-	dBc
t _{on}	turn-on time		[5]	-	-	2	μs
t _{off}	turn-off time		[5]	-	-	1	μs

[1] Power at GPS front-end input = power at LNA input + attenuation BPF1.

[2] Out of band.

[3] $f_1 = 1713 \text{ MHz}; f_2 = 1851 \text{ MHz}; P_1 = P_2 = +10 \text{ dBm}.$

[4] Relative to f = 1575 MHz.

[5] Within 10 % of the final gain.

9. Test information

9.1 Quality information

All qualification tests are performed according AEC-Q100 except for read point testing (final test of qualification sample). Which is done only at room temperature.

As part of the zero defect program, the following is part of the industrial test flow:

- Part Average Testing
- Maverick Lot Handling at assembly factory

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10. Package outline



Fig 33. Package outline SOT886 (XSON6)

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11. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices. Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or

equivalent standards.

12. Abbreviations

Table 12. Abbreviations				
Acronym	Description			
AEC	Automotive Electronics Council			
ATM	Automated Teller Machine (cash dispenser)			
BPF	Band-Pass Filter			
ESD	ElectroStatic Discharge			
GLONASS	GLObal NAvigation Satellite System			
GNSS	Global Navigation Satellite System			
GPS	Global Positioning System			
HBM	Human Body Model			
MMIC	Monolithic Microwave Integrated Circuit			
PCB	Printed Circuit Board			
SAW	Surface Acoustic Wave			
SiGe:C	Silicon Germanium Carbon			

13. Revision history

Table 13. Revision history						
Document ID	Release date	Data sheet status	Change notice	Supersedes		
BGU7004 v.3	20170118	Product data sheet	-	BGU7004 v.2		
Modifications:	Section 1: ad	<u>Section 1</u> : added GPS1103M according to our new naming convention				
BGU7004 v.2	20150220	Product data sheet	-	BGU7004 v.1		
Modifications:		 The title of this data sheet has been changed. <u>Section 1.3 on page 1</u>: Added GLONASS, Galileo and Compass (BeiDou) to the possible applications. 				
	• Section 14.3	 <u>Section 11 on page 17</u>: ESD information has moved from Section 1.1 to this section. <u>Section 14.3 on page 18</u>: Adjusted the disclaimers with respect to "suitability to use in automotive applications" and "Translations". 				
BGU7004 v.1	20110705	Product data sheet	-	-		

Product data sheet

14. Legal information

14.1 Data sheet status

Document status[1][2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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